Next Generation Technologies in Electronic Packaging and Production ½ Day Course

ABSTRACT
Product and manufacturing engineers are often required to select, review, and/or validate new technologies that are selected by the internal design team or a supplier. Product managers and technologists are expected to be aware of evolutions and revolutions in the various components that comprise an electronic product or system. However, obtaining the information necessary to perform both tasks is difficult with the given system of information dissemination that is currently present within the electronics marketplace.

Academic publications, trade journals, and industry conferences are often segmented in a manner not consistent with actual product architecture or the multi-functional teams created within corporate organizations. The need for either rapid news easily digestible or highly rigorous, scientific studies can create a confusing array of pure marketing mush or comprehensive and detailed data on technologies that will never be incorporated into actual product.

The purpose of this course is to clearly identify new technologies within the component packaging, printed board, circuit assembly, and thermal solution regime, provide insight into the benefits of such technologies, and concisely discuss some of the challenges and risks of implementing these technologies. To maintain in close alignment with the leading adopters in the electronics industry, the list of technologies provided in this abstract may change before this presentation is finalized

OUTLINE

- Component Packaging
  - Stacked die
  - QFN
- Printed Board
  - Nanofinish
  - 8 mil drill
  - Filled vias
  - Embedded resistors and capacitors
- Assembly
  - Occam and other embedded active solutions
  - 2nd generation Pb-free alloys (SnCu-Ni, low Ag SAC, etc.)
  - 01005 components
  - Nanosolder
- Thermal Solutions
  - Graphite
  - B-Temp
  - Stablcor
  - Reactive Nanofoil

Who Should Attend?
Design Personnel (managers and engineers), Product Personnel (managers and engineers), Reliability Personnel (managers and engineers), and Executives responsible for insertion of new technologies.

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